

Title (en)
METHOD AND DEVICE FOR CONNECTING SEMICONDUCTOR OR INTERPOSER COMPONENTS TO A SUPPORTING STRIP AND THE USE OF SAID DEVICE

Title (de)
VERFAHREN UND VORRICHTUNG ZUM VERBINDEN VON HALBLEITERELEMENTEN ODER INTERPOSERN MIT EINEM TRÄGERBAND UND VERWENDUNG EINER DERARTIGEN VORRICHTUNG

Title (fr)
PROCEDE ET DISPOSITIF POUR RELIER DES ELEMENTS A SEMI-CONDUCTEURS OU DES INTERPOSEURS A UNE BANDE SUPPORT ET UTILISATION D'UN TEL DISPOSITIF

Publication
EP 1849341 A2 20071031 (DE)

Application
EP 06708208 A 20060213

Priority
• EP 2006050866 W 20060213
• DE 102005006978 A 20050215

Abstract (en)
[origin: DE102005006978B3] Method for joining semiconductor components (2) with a flexible support band (1) comprises moving an endless band parallel to the running direction (5) of the support band between first heating elements (7a-7c) and the semiconductor components and between a second heating element and the semiconductor components whilst the first heating elements exert a first pressure using a spring action. An independent claim is also included for a device for joining semiconductor components with a flexible support band.

IPC 8 full level
H05K 13/00 (2006.01)

CPC (source: EP)
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Citation (search report)
See references of WO 2006087301A2

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DE 102005006978 B3 20060608; EP 1849341 A2 20071031; WO 2006087301 A2 20060824; WO 2006087301 A3 20061207

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